



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshiyuki Yanagisawa et al.  
Appl. No.: 10/062,776  
Conf. No.: 3355  
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Title: DEVICE TRANSFER METHOD AND PANEL  
Art Unit: 2812  
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Docket No.: 112857-315

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Commissioner for Patents  
P.O. Box 1450  
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STATEMENT OF RELEVANCE

Sir:

Japanese laid open application 5-315646 discloses a method of cutting a sapphire substrate. A gallium nitride semiconductor layer formed on the sapphire substrate is cut by a dicer to form grooves deeper than the gallium nitride layer. The sapphire substrate is thinned by polishing a back surface of the substrate. Scribing lines are formed on the sapphire substrate via the grooves by a scriber. The sapphire substrate is then forcibly cut into chips by an external force. Chips can be smoothly cut without cracking and or chipping the cut plains of the sapphire substrate.

Respectfully submitted,

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